

EMIF02-MIC07F3

EMI filter and ESD protection

Features

- EMI symmetrical (I/O) low-pass filter
- high efficiency in EMI/ESD protection
- lead-free package
- very thin package
- high reliability offered by monolithic integration
- high reduction of parasitic elements through integration and wafer level packaging

Complies with the following standards

- IEC 61000-4-2 level 4 (on external pins B1 and C1):
 - ±15 kV (air discharge)
 - ±8 kV (contact discharge)
- IEC 61000-4-2 level 1 (on external pins):
 - ±2 kV (air discharge)
 - ±2 kV (contact discharge)

Applications

Where EMI filtering in ESD sensitive equipment is required:

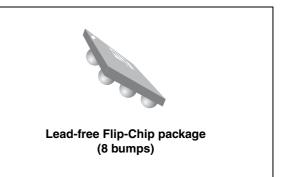
- mobile phones and communication systems
- computers, printers and MCU Boards

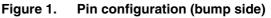
Description

The EMIF02-MIC07F3 chip is a highly integrated audio filter device designed to suppress EMI/RFI noise in all systems subjected to electromagnetic interference.

This filter includes ESD protection circuitry, which prevents damage to the protected device when subjected to ESD surges up to 15 kV.

TM: IPAD is a trademark of STMicroelectronics.





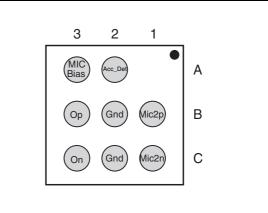
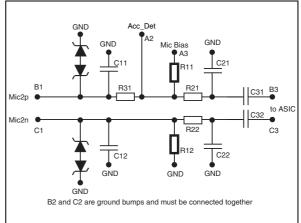


Figure 2. Schematic



October 2010

Doc ID 17052 Rev 2

1 Characteristics

Table 1.	Absolute	ratings	(limitina	values)
	Absolute	raungs	(initiality	values	,

Symbol	Parameter and test conditions	Value	Unit
V _{PP}	 Pins B1 and C1, ESD discharge IEC 61000-4-2, level 4: air discharge contact discharge Pins A2, A3, B3, C3, ESD discharge IEC 61000-4-2, level 1 air discharge contact discharge 	15 8 2 2	kV
PD	Power dissipation at $T_{amb} = 25 \ ^{\circ}C$	60	mW
T _{op}	Operating temperature range	-40 to +85	°C
T _{stg}	Storage temperature range	-55 to +150	°C

Figure 3. Electrical characteristics (definitions)

Symbo	ol	Parameter	
V _{BR}	=	Breakdown voltage	
V _{CL}	=	Clamping voltage	
I _{RM}	=	Leakage current @ V _{BM}	
V _{RM}	=	Stand-off voltage	
I _F	=	Forward current	
I _{PP}	=	Peak pulse current	
I _R	=	Breakdown current	
V _F	=	Forward voltage drop	
R _d	=	Dynamic impedance	
αT	=	Voltage temperature	

Table 2.	Electrical characteristics - values (T _{amb} = 25 °C)
----------	--

Symbol	Test conditions	Min.	Тур.	Max.	Unit
V _{BR}	I _R = 1 mA	7			V
I _{RM}	V _{RM} = 3 V per line		50	200	nA
R ₁₁		1900	2000	2100	
R ₁₂		800	1000	1200	Ω
R_{21}, R_{22}		1760	2200	2640	52
R ₃₁		20	25	30	
C ₁₁ , C ₁₂	$V_{\text{line}} = 0 \text{ V}, V_{\text{osc}} = 30 \text{ mV}, \text{ F} = 1 \text{ MHz}$	0.66	0.83	1	
C ₂₁ , C ₂₂	(measured under zero light conditions and with	1	1.25	1.5	nF
C ₃₁ , C ₃₂	bumps B2 and C2 connected together)	7	8.75	10.5	



Figure 4.

Symbol	Condition	Max. Value	Unit
Ripple	Between 5 Khz and 20 kHz	2	dB
THD+N	-21dBV fully differential between MICn and MICp 1kHz	0.009	%

Table 3. Dynamic characteristics $(T_{amb} = 25^{\circ} C)^{(1)}$

1. Dynamic characteristics are guaranteed by design and not production tested

Attenuation versus frequency

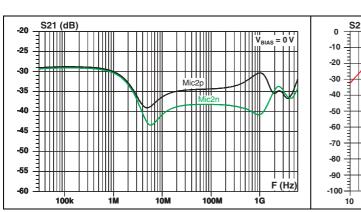
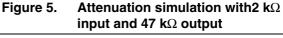


Figure 6. Analog crosstalk measurement



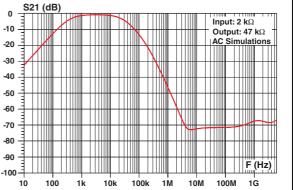


Figure 7. ESD response to IEC 61000-4-2 on one input $V_{(in)}$ and on one output

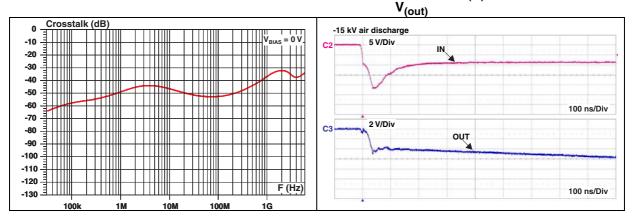
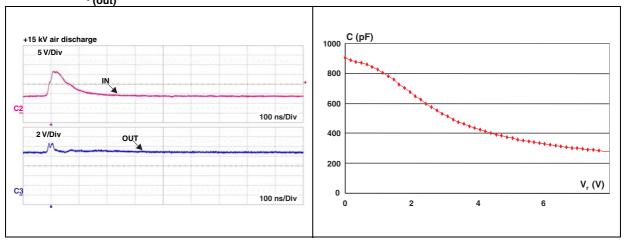
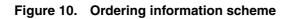


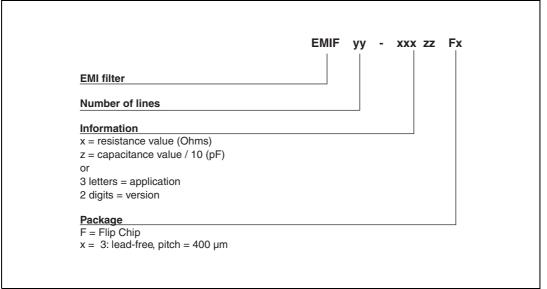
Figure 8. ESD response to IEC 61000-4-2 on Figure 9. one input V_(in) and on one output V_(out)



e 9. Line capacitance versus applied voltage (C11)

2 Ordering information scheme







3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: <u>www.st.com</u>. ECOPACK[®] is an ST trademark.

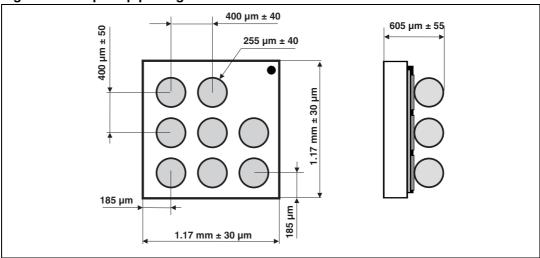
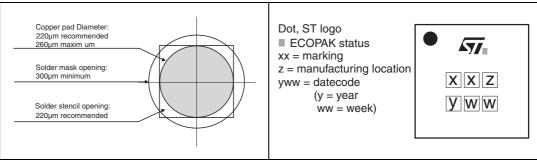




Figure 12. Footprint recommendations Figure 13. Marking





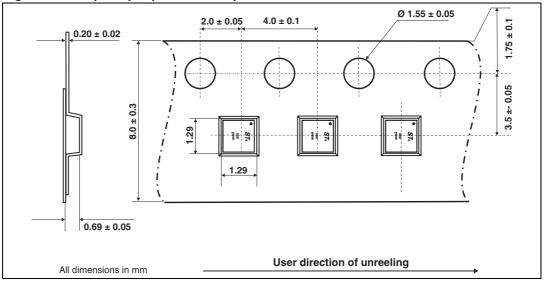


Figure 14. Flip-Chip tape and reel specification

4 Ordering information

Table 4.Ordering information

Order code	Order code Marking		Weight	Base qty	Delivery mode
EMIF02-MIC07F3	JE	Flip Chip	1.8 mg	5000	Tape and reel 7"

Note:

More information is available in the application notes AN2348: "Flip Chip: Package description and recommendations for use" AN1751: "EMI Filters: Recommendations and measurements"

5 Revision history

Table 5.Document revision history

Date	Revision	Changes
16-Mar-2010	1	Initial release.
13-Oct-2010	2	Added Table 3.



Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2010 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan -Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com



Doc ID 17052 Rev 2